

Amendments to the Abstract:

Please replace the current abstract with the following replacement Abstract:

Abstract

An electrical power circuit assembly including an insulated metal substrate (IMS) printed circuit board (PCB), a filter (PCB), and one or more bus bars disposed between the IMS PCB and the filter (PCB), the bus bar geometry configured to reduce the inductance between semiconductor power devices on the IMS PCB and capacitors on the filter PCB. For one embodiment, low profile bus bars are used between the IMS PCB and a fiberglass PCB. The fiberglass PCB has a plurality of filter capacitors electrically connected across the bus structure. The geometry and layout of the bus bars provides a connection from the IMS PCB to the fiberglass PCB with very low parasitic inductance between surface mounted semiconductor power devices on the IMS PCB and filter capacitors on the fiberglass PCB.